L Number	Hits	Search Text	DB	Time stamp
1	64234	451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:47
2	1315	pressure adj sensitive adj paper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:47
3	1	451/$.ccls. and (pressure adj sensitive adj paper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:46
4	32466	451/$.ccls.	USOCR	2004/08/10 09:47
5	113	pressure adj sensitive adj paper	USOCR	2004/08/10 09:47
6	0	451/$.ccls. and (pressure adj sensitive adj paper)	USOCR	2004/08/10 09:47
10	3275840	condition conditioner conditioning conditions conditioners conditioned	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:49
11	2709203	wafer wafers substrate substrates semiconductor semiconductors	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:49
12	2021902	sensor sensors sensing sense sensed senses	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:49
13	10377	(condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:11
14	3212959	pressure pressures	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:50
15	296272	database databases (data adj (base bases))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:51
16	2	((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses)) same (pressure pressures) same (database databases (data adj (base bases)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:53
17	14	((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses)) and ((pressure pressures) with (database databases (data adj (base bases))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:54
18	247	451/$.ccls. and ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:58

19	63	(451/$.ccls. and ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses))) and conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:01
20	0	((451/$.ccls. and ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses))) and conditioner) and (pressure adj sensitive adj paper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 09:59
21	2894295	determine determining determines determined	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:02
22	4118120	(sensor sensors sensing sense sensed senses) or (determine determining determines determined)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:03
23	42	(pressure adj sensitive adj paper) with ((sensor sensors sensing sense sensed senses) or (determine determining determines determined))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:07
24	0	"10" with ((sensor sensors sensing sense sensed senses) or (determine determining determines determined)) with (pressure adj sensitive adj paper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:07
25	3	(condition conditioner conditioning conditions conditioners conditioned) with ((sensor sensors sensing sense sensed senses) or (determine determining determines determined)) with (pressure adj sensitive adj paper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:10
26	3	((condition conditioner conditioning conditions conditioners conditioned) with (pressure adj sensitive adj paper)) same ((sensor sensors sensing sense sensed senses) or (determine determining determines determined))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:11
27	3023	(condition conditioner conditioning conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor sensors sensing sense sensed senses)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:13
28	0	((condition conditioner conditioning conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor sensors sensing sense sensed senses)) and (pressure adj sensitive adj paper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:13
29	167	((condition conditioner conditioning conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor sensors sensing sense sensed senses)) with conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:13
30	3	(((condition conditioner conditioning conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor sensors sensing sense sensed senses)) with conditioner) and 451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:15

31	749	(polishing adj pad) with conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:15
32	0	(pressure adj sensitive adj paper) and ((polishing adj pad) with conditioner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:15
33	25	((condition conditioner conditioning conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor sensors sensing sense sensed senses)) and ((polishing adj pad) with conditioner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:16
34	71653	(uniformity uniform) with (pressure pressures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:17
35	292	((uniformity uniform) with (pressure pressures)) and ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:17
36	71653	((uniformity uniform) with (pressure pressures)) samel13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:17
37	44	((uniformity uniform) with (pressure pressures)) same ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed senses))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:19
38	0	uniformity near3 pressure near3 conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:19
39	0	uniformity near5 pressure near5 conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:20
40	0	(uniformity adj3 pressure) near5 conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:20
41	1682	(uniformity adj3 pressure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:20
43	11	(((uniformity adj3 pressure)) and conditioner) and polishing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:20
42	48	((uniformity adj3 pressure)) and conditioner	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 10:35

| 44 | 11 | ((polishing adj pad) with conditioner) with ((uniformity uniform) with (pressure pressures)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/10 10:58 |
| 45 | 4 | "6477447" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/10 10:59 |